

**NAP100 (Sn/0.7Cu/0.05Ni)****Lead Free Solder Bar**

- (1) **Application** This product is suitable for the tin spraying operation system on the surface of the PCB board, and is widely used while applying the wave soldering operation in the automatic lead-free soldering furnace.

Recommended Operation Temperature 255~270°C

- (2) **Characteristic**

2.1 Alloy Composition

Item	Specification						
	Composition(%)			Impurity (%)			
Standard	Sn	Cu	Ni	Pb	Ag	Sb	Zn
			0.05+/-0.01	<0.05	<0.1	<0.1	<0.001
	Bal.	0.7+/-0.2	Al	Fe	As	Bi	Cd
			<0.002	<0.02	<0.03	<0.1	<0.002

2.2 Physical Characteristic

Alloy Composition	Melting Point	Specific Gravity
Sn/0.7Cu/0.05Ni	227°C	7.32g/cm ³

- (3) **Packaging**

Type			
Dimen.	(L)	Top Ladder 325mm	Bottom ladder 330mm
	(H)	15mm	
	(W)	Top Ladder 17mm	Bottom Ladder 21mm
	Weight	~0.7 kg	
Package	Package Material	Net Weight / box	Box Dimension
	Paper Carton	20kgs	360 × 190 × 65mm

- (4) **Recommendation** It is recommended to add NAP100CX (Sn/0.05Ni) copper-free alloy to maintain the "cop concentration in the tin molten. Our company provides valet alloy inspection services.
- (5) **Storage** Keep in dark , cool place and keep away from the sun or fire place.
- (6) **Validity** 1 year in right storage.

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